BGA Heat Sink - High Performance maxiFLOW/superGRIP



ATS Part#:

Description:



ATS-X50150B-C1-R0

15.00 x 15.00 x 7.50 mm BGA Heat Sink - High Performance maxiFLOW/superGRIP

Heat Sink Type:

maxiFLOW Heat Sink Attachment: superGRIP

Equivalent Part Number: N/A

*Image above is for illustration purpose only.

Features & Benefits

- Designed for 15 x 15 mm components. •
- Requires minimal space around the component's perimeter; ideal for densely populated PCBs •
- Allows the heat sink to be detached and reattached without damaging the component or the PCB, an important feature in the event a • PCB may need to be reworked
- Strong, uniform attachment force helps achieve maximum performance from phase-changing TIMs
- Eliminates the need to drill mounting holes in the PCB .

Thermal Performance

		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	19.7 °C/W	15.9 °C/W	13.8 °C/W	12.3 °C/W	11.2 °C/W	10.4 °C/W	9.7 °C/W
	Ducted Flow	14.6	N/A	N/A	N/A	N/A	N/A	N/A

Product Detail

Schematic Image	Dimension A	Dimension B	Dimension C	Dimension D	ТІМ	Finish
	15.00 mm	15.00 mm	7.50 mm	27.9 mm	T766	BLUE-ANODIZED
•Image above is for illustration purpose only.	 Dimension Thermal papplication ATS resense performar ATS certifier 	rves the right to upda	eight from the bottor e provided for referen ate or change its pro- k assembly is RoHS	nce only. Actual perf ducts without notice -6 and REACH com	ormance to improv	may vary by

For more information, to find a distributor or to place an order, please contact us at 781-769-2800 (North America), sales@qats.com or www.qats.com.

